

Outsourced Semiconductor Assembly and Test Market: Trends, Forecast and Competitive Analysis

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Abstracts

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The future of the global outsourced semiconductor assembly and test (OSAT) market looks promising with opportunities in the computer & networking, consumer electronics, industrial electronics, and telecom industries. The global OSAT market is expected to reach an estimated \$45 billion by 2027 with a CAGR of 4.6% from 2021 to 2027. The major drivers for this market are increasing semiconductor content within electronics products to provide greater functionality and higher levels of performance, growth in demand for smartphones and internet connected devices, and increasing electronic content in automotive for safety, navigation, fuel efficiency, emission reduction, and entertainment system.

Evolution of OSAT Opportunities

OSAT opportunities have evolved through number of stages as presented in figure below:

Emerging Trends in the OSAT Market

Emerging trend, which has a direct impact on the dynamics of the industry, includes miniaturization and higher functionality semiconductors.

A total of 107 figures / charts and 68 tables are provided in this 200-page report to help in your business decisions. A sample figure with insights is shown below. To learn the scope of benefits, companies researched, and other details of the facial cleanser market

report, please download the report brochure.

OSAT Market by Segment

The study includes a forecast for the global OSAT market by service type, packaging type, end use industries, and region as follows:

OSAT Market by Service Type [Value (\$M) shipment analysis for 2016 – 2027]:

Assembly & Packaging

Testing

OSAT Market by Packaging Type [Value (\$B) shipment analysis for 2016 – 2027]:

Wire Bond

Flip Chip

Wafer Level

Others

OSAT Market by End Use Industry [Value (\$M) shipment analysis for 2016 – 2027]:

Telecommunication

Computer & Networking

Consumer Electronics

Industrial Electronics

Others

OSAT Market by Region [Value (\$M) shipment analysis for 2016 – 2027]:

North America

US

Canada

Mexico

Europe

Germany

The United Kingdom

France

Asia Pacific

China

Japan

South Korea

The Rest of the World

List of OSAT Companies

Companies in the market compete on the basis of product quality offered. Major players in this market focus on expanding their manufacturing facilities, R&D investments, infrastructural development, and leverage integration opportunities across the value chain. With these strategies OSAT companies cater increasing demand, ensure competitive effectiveness, develop innovative products & technologies, reduce production costs, and expand their customer base. Some of the OSAT companies profiled in this report includes.

Advanced Semiconductor Engineering

Amkor

Jiangsu Changjiang Electronics Technology

Siliconware Precision Industries Co. Ltd.

PTI(Powertech Technology Inc.)

Tianshui Huatian Technology co. Ltd

Tongfu Microelectronics co. Ltd

United test and assembly center Ltd

King Yuan Electronics co, Ltd.

ChipMOS

OSAT Market Insight

Lucintel forecasts that computer and networking will remain the largest end use segment over the forecast period due to increasing demand of semiconductors in data centers, network infrastructure, and storage applications.

Wire bond will remain the largest packaging type over the forecast period, as wire bond packaging is cost effective solution for low to medium pin count applications.

Asia Pacific will remain the largest region over the forecast period and it is also expected to witness the highest growth over the over the forecast period due to a growing adoption of IoT (internet of things), increasing electronic content per vehicles, and growing industrial automation in countries such as China, Taiwan, and India.

Features of OSAT Market

Market Size Estimates:OSAT market size estimation in terms of value (\$B)

Trend and Forecast Analysis:Market trends (2016-2021) and forecast (2022-2027) by various segments and regions.

Segmentation Analysis:Market size by service type, packaging type, and end use industries.

Regional Analysis:OSAT market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

Growth Opportunities:Analysis of growth opportunities in different service type, packaging type, end use industries, and regions for the OSAT market.

Strategic Analysis:This includes M&A, new product development, and competitive landscape for the OSAT market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

FAQ

Q1. What is the OSAT market size?

Answer:The global OSAT market is expected to reach an estimated \$45 billion by 2027

Q2. What is the growth forecast for OSAT market?

Answer:The OSAT market is expected to grow at a CAGR of 4.6% from 2021 to 2027.

Q3. What are the major drivers influencing the growth of the OSAT market?

Answer: The major drivers for this market are increasing semiconductor content within electronics products to provide greater functionality and higher levels of performance, growth in demand for smartphones and internet connected devices, and increasing electronic content in automotive for safety, navigation, fuel efficiency, emission reduction, and entertainment system.

Q4. What are the major applications or end use industries for OSAT?

Answer: Computer and networking and consumer electronics are the major end use industries for facial cleanser.

Q5. What are the emerging trends in OSAT market?

Answer: Emerging trend, which has a direct impact on the dynamics of the industry, includes miniaturization and higher functionality semiconductors.

Q6. Who are the key OSAT companies?

Answer: Some of the key OSAT companies are as follows:

Advanced Semiconductor Engineering

Amkor

Jiangsu Changjiang Electronics Technology

Siliconware Precision Industries Co. Ltd.

PTI(Powertech Technology Inc.)

Tianshui Huatian Technology co. Ltd

Tongfu Microelectronics co. Ltd

United test and assembly center Ltd

King Yuan Electronics co, Ltd.

ChipMOS

Q7. Which OSAT product segment will be the largest in future?

Answer: Lucintel forecasts that wire bond will remain the largest packaging type over the forecast period, as wire bond packaging is cost effective solution for low to medium pin count applications.

Q8: In OSAT market, which region is expected to be the largest in next 5 years?

Answer: Asia Pacific is expected to remain the largest region and witness the highest growth over next 5 years

Q9. Do we receive customization in this report?

Answer: Yes, Lucintel provides 10% Customization Without any Additional Cost.

This report answers following 11 key questions

Q.1 What are some of the most promising potential, high growth opportunities for the global OSAT market by service type (assembly/packaging and testing), end use industry (telecommunication & devices, computer & networking, consumer electronics, industrial electronics, others), packaging type (wire bond, flip chip, wafer level, and others), and region (North America, Europe, Asia Pacific, and the Rest of the World)?

Q. 2 Which segments will grow at a faster pace and why?

Q.3 Which regions will grow at a faster pace and why?

Q.4 What are the key factors affecting market dynamics? What are the drivers and challenges of the market?

Q.5 What are the business risks and threats to the market?

Q.6 What are the emerging trends in this market and the reasons behind them?

Q.7 What are the changing demands of customers in the market?

Q.8 What are the new developments in the market? Which companies are leading these developments?

Q.9 Who are the major players in this market? What strategic initiatives are being implemented by key players for business growth?

Q.10 What are some of the competitive products and processes in this area and how big of a threat do they pose for loss of market share via material or product substitution?

Q.11 What M & A activities have taken place in the last 5 years in this market?

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- 7.8: United test and assembly center Ltd
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